

REMARKS/ARGUMENTS

Reexamination of the captioned application is respectfully requested.

Claims 1, 2 and 3 have been amended to include the limitation of claim 20, e.g., that a grain size of the polycrystalline microstructure is uniformly increased in length and width as the polycrystalline microstructure is formed in the semiconductor material layer by the lateral solidification from the boundary of the region. Claim 20 has been cancelled without prejudice or disclaimer. Applicants believe that, e.g., the amendatory limitation is not taught or suggested by the applied references.

The Examiner stated that the description in ¶[0033] of Teramoto teaches providing a high thermal conductivity material. But ¶[0033] of Teramoto does not describe that the materials listed in that paragraph have high thermal conductivity. Rather Teramoto states that "... there is no place to which heat escapes ..." in ¶[0171] (*see*, e.g., Example 5 of Teramoto). From the description of Teramoto, it seems that the insulating film in Teramoto has low thermal conductivity.

Applicants apply a high thermal conductivity material having thermal conductivity at least 10 W/mK, and promote heat spreading and uniform cooling in the region, whereby after irradiation a polycrystalline microstructure is formed in the semiconductor material layer by lateral solidification from a boundary of the region (on page 5, lines 5-9 in the present specification). Teramoto and other applied references do not describe the high thermal conductivity material having thermal conductivity at least 10 W/mK.

In view of the foregoing and other considerations, all claims are deemed in condition for allowance. Accordingly, Applicant respectfully requests that all prior art rejections be withdrawn. A formal indication of allowability is earnestly solicited.

The Commissioner is authorized to charge the undersigned's deposit account #14-1140 in whatever amount is necessary for entry of these papers and the continued pendency of the captioned application.

Should the Examiner feel that an interview with the undersigned would facilitate allowance of this application, the Examiner is encouraged to contact the undersigned.

Respectfully submitted,

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